

X7R with KONNEKT Technology

Overview

X7R with KONNEKT™ technology surface mount capacitors are designed for applications where higher capacitance and voltage are needed without requiring additional board space. KONNEKT high density packaging technology uses a proprietary Transient Liquid Phase Sintering (TLPS) material to create a surface mount multi-chip solution for high density packaging.

Benefits

Commercial and Automotive grade (AEC-Q200)
Stacked design saves PCB area.
Lead (Pb)-free, RoHS, and REACH compliant
Surface mount capable with standard reflow

Part Number System

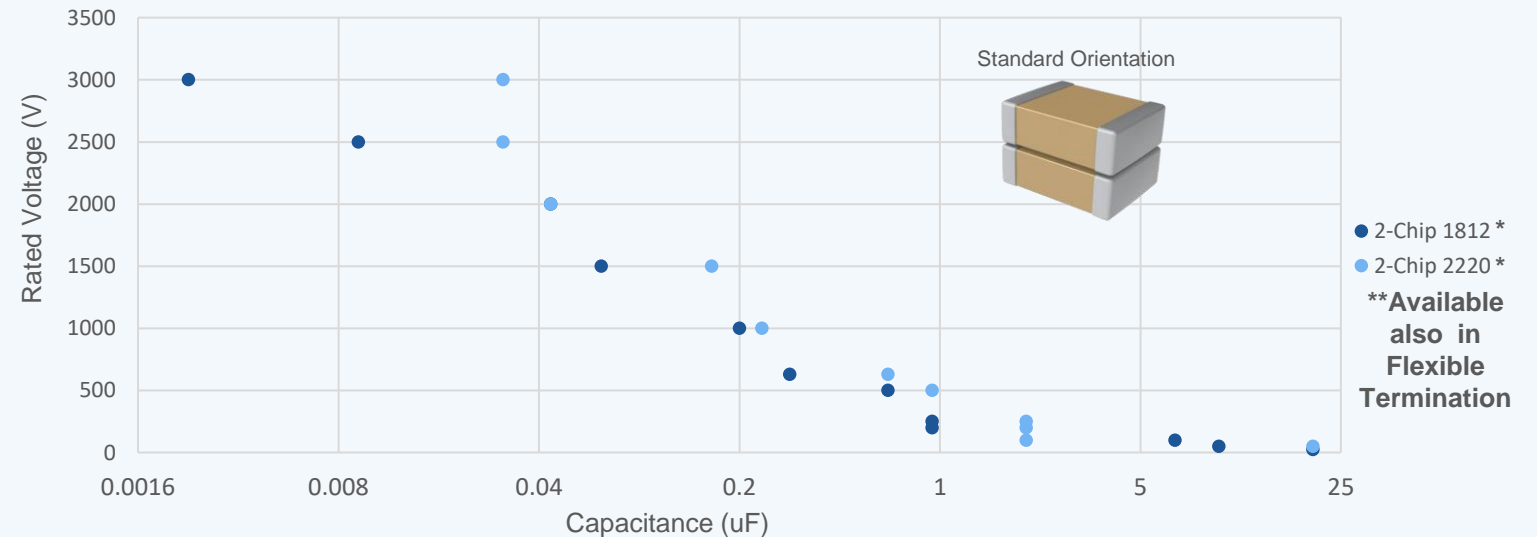
C 1812 C 884 K C G L C

Termination – C: 100% Sn
Subclass – L: KONNEKT
Dielectric – R: X7R
Rated Voltage – C: 500 V
Tolerance code – K: 10%
Cap Code – 944: 94x10⁴ pF
Specification – C: Standard / X: Flexible termination
Case Size (L" x W")
Series - Ceramic

Electrical Characteristics

Operating Temperature –55°C to +125°C
Rated Capacitance 2.4 nF – 20 uF (±10% tol.)
Rated Voltage 25 V – 3,000 V
EIA Case Size 1812 and 2220

X7R with KONNEKT Selection Guide



Applications

SMPS (Switch Mode Power Supplies)
Lighting ballasts, HID lighting
DC/DC Converters
Telecom equipment

Industrial and medical equipment
Filters
Snubbers
DC Blocking

<https://ec.kemet.com/konnekt>